Nch 650V 20A Power MOSFET

| V_{DSS} | 650V |
|----------------------------|--------|
| R _{DS(on)} (Max.) | 0.205Ω |
| I _D | ±20A |
| P_D | 231W |

FD 23

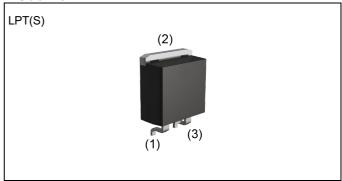
Features

- 1) Low on-resistance
- 2) Ultra fast switching speed
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant

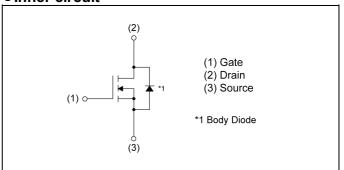
Application

Switching

Outline



•Inner circuit



Packaging specifications

| Packing | Embossed Tape |
|---------------------------|---------------|
| Packing code | TL |
| Marking | R6520KNJ |
| Basic ordering unit (pcs) | 1000 |

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

| Parameter | Symbol | Value | Unit | |
|---|--------------------|--------------------|------|----|
| Drain - Source voltage | | V_{DSS} | 650 | V |
| Continuous drain current (T _c = 25 | 5°C) | I _D *1 | ±20 | Α |
| Pulsed drain current | I _{DP} *2 | ±60 | Α | |
| static | | V_{GSS} | ±20 | V |
| Gate - Source voltage AC(f>1Hz) | | | ±30 | V |
| Avalanche current, single pulse | <u>,</u> | I _{AS} | 3.4 | Α |
| Avalanche energy, single pulse | | E _{AS} *3 | 444 | mJ |
| Power dissipation (T _c = 25°C) | P _D | 231 | W | |
| Junction temperature | T _j | 150 | °C | |
| Operating junction and storage te | T _{stg} | -55 to +150 | °C | |

●Thermal resistance

| Davanatav | Curah al | Values | | | 1.1:4 |
|--|----------------------|--------|------|------|-------|
| Parameter | Symbol | Min. | Тур. | Max. | Unit |
| Thermal resistance, junction - case | R _{thJC} *4 | - | - | 0.54 | °C/W |
| Thermal resistance, junction - ambient | R _{thJA} *5 | - | - | 80 | °C/W |
| Soldering temperature, wavesoldering for 10s | T _{sold} | - | - | 265 | °C |

• Electrical characteristics ($T_a = 25$ °C)

| Davameter | Cymah al | Conditions | Values | | | Linit |
|---|------------------------|--|--------|-------|-------|-------|
| Parameter | Symbol | Conditions | Min. | Тур. | Max. | Unit |
| Drain - Source breakdown voltage | V _{(BR)DSS} | $V_{GS} = 0V$, $I_D = 1mA$ | 650 | - | - | V |
| | | V _{DS} = 650V, V _{GS} = 0V | | | | |
| Zero gate voltage drain current | I _{DSS} | $T_j = 25^{\circ}C$ | - | - | 100 | μΑ |
| | | $T_j = 125^{\circ}C$ | ı | - | 1000 | |
| Gate - Source leakage current | I _{GSS} | $V_{GS} = \pm 20V$, $V_{DS} = 0V$ | 1 | - | ±100 | nA |
| Gate threshold voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_{D} = 630 \mu A$ | 3 | - | 5 | V |
| | | $V_{GS} = 10V, I_D = 9.5A$ | | | | |
| Static drain - source on - state resistance | R _{DS(on)} *6 | $T_j = 25^{\circ}C$ | - | 0.185 | 0.205 | Ω |
| | | $T_j = 125^{\circ}C$ | - | - | 1 | |
| Gate resistance | R_{G} | f = 1MHz, open drain | - | 2.4 | - | Ω |

● Electrical characteristics (T_a = 25°C)

| Davameter | Cymah al | Conditions | Values | | | Unit |
|------------------------------|------------------------|---------------------------------------|--------|------|------|------|
| Parameter | Symbol | Symbol Conditions - | | Тур. | Max. | Unit |
| Input capacitance | C _{iss} | V _{GS} = 0V | - | 1550 | - | |
| Output capacitance | C _{oss} | V _{DS} = 25V | - | 1450 | - | pF |
| Reverse transfer capacitance | C _{rss} | f = 1MHz | 1 | 45 | 1 | |
| Turn - on delay time | t _{d(on)} *6 | $V_{DD} \simeq 300V$, $V_{GS} = 10V$ | - | 30 | - | |
| Rise time | t _r *6 | I _D = 10A | - | 50 | - | |
| Turn - off delay time | t _{d(off)} *6 | $R_L \simeq 30\Omega$ | - | 75 | - | ns |
| Fall time | t _f *6 | $R_G = 10\Omega$ | - | 30 | - | |

● Gate charge characteristics (T_a = 25°C)

| Darameter | Cumb al | Conditions | Values | | | l leit |
|----------------------|-----------------------------|--|--------|------|------|--------|
| Parameter | Parameter Symbol Conditions | | Min. | Тур. | Max. | Unit |
| Total gate charge | Q_g^{*6} | V _{DD} ≈ 300V | - | 40 | - | |
| Gate - Source charge | Q _{gs} *6 | I _D = 20A | - | 10 | - | nC |
| Gate - Drain charge | ${\sf Q_{gd}}^{*6}$ | V _{GS} = 10V | - | 17 | - | |
| Gate plateau voltage | V _(plateau) | V _{DD} ≈ 300V, I _D = 20A | - | 6.8 | - | V |

^{*1} Limited only by maximum channel temperature allowed.

^{*2} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*3} L \doteqdot 70mH, V_{DD}=50V, R_G=25 Ω , STARTING T_i=25 $^{\circ}$ C

^{*4} T_C=25°C

^{*5} Mounted on an epoxy PCB FR4 (25mm x 27mm x 0.8mm)

^{*6} Pulsed

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

| Parameter | Symbol | Conditions | Values | | | Unit |
|-------------------------------|--------------------|---|--------|------|------|-------|
| - Farameter | Symbol | Conditions | Min. | Тур. | Max. | Offic |
| Source current | I _S *1 | T 05% | | - | 20 | Α |
| Pulsed source current | I _{SP} *2 | T _C = 25°C | 1 | - | 60 | Α |
| Source-Drain voltage | V _{SD} *6 | $V_{GS} = 0V, I_{S} = 20A$ | - | - | 1.5 | V |
| Reverse recovery time | t _{rr} *6 | | - | 500 | - | ns |
| Reverse recovery charge | Q _{rr} *6 | I _S = 20A di/dt = 100A/μs | - | 8 | - | μC |
| Peak reverse recovery current | I _{rr} *6 | | - | 32 | - | А |

Fig.1 Power Dissipation Derating Curve

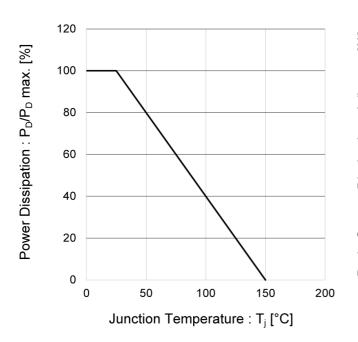


Fig.2 Drain Current Derating Curve

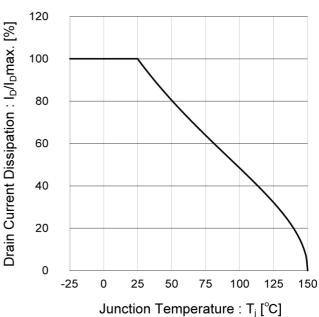


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

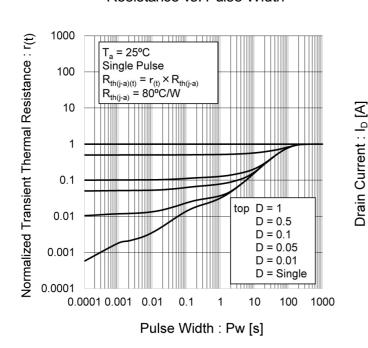


Fig.4 Maximum Safe Operating Area

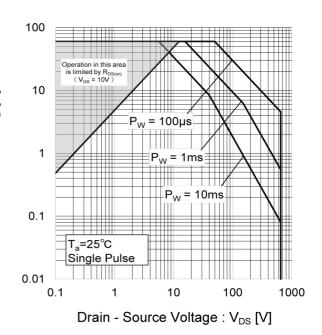


Fig.5 Avalanche Energy DeratingCurve vs. Junction Temperature

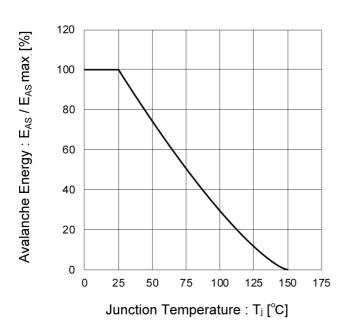


Fig.6 Breakdown Voltage vs. Junction Temperature

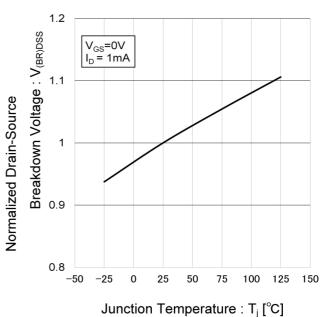


Fig.7 Typical Output Characteristics(I)

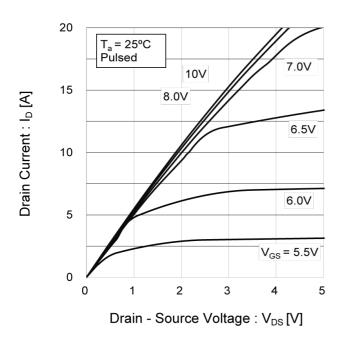
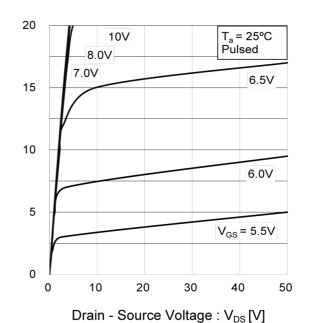


Fig.8 Typical Output Characteristics(II)



Drain Current : I_D [A]

Fig.9 Typical Transfer Characteristics

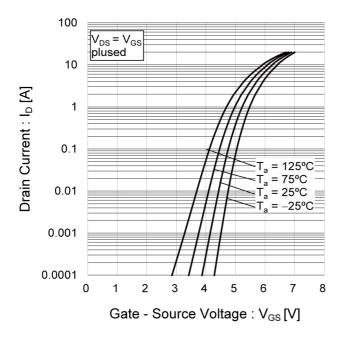


Fig.10 Normalized Gate Threshold .

Voltage vs Junction Temperature

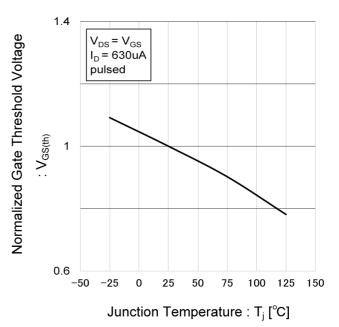


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

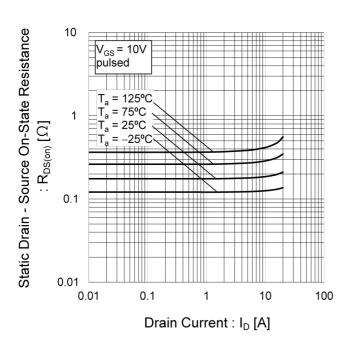


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

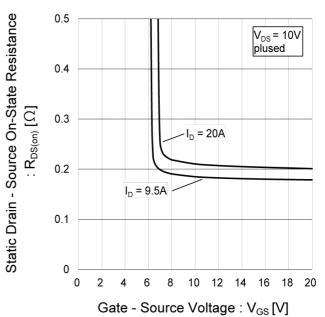


Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

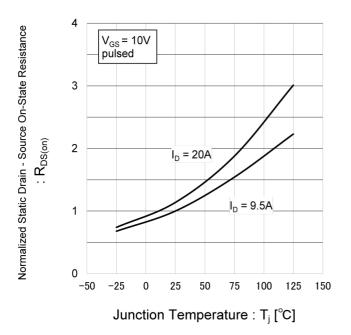
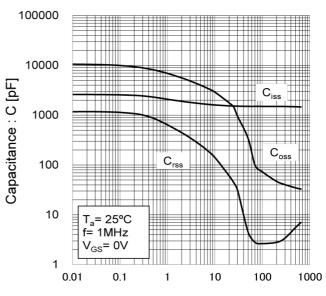


Fig.14 Typical Capacitance vs.

Drain - Source Voltage



Drain - Source Voltage: V_{DS}[V]

Fig.15 Switching Characteristics

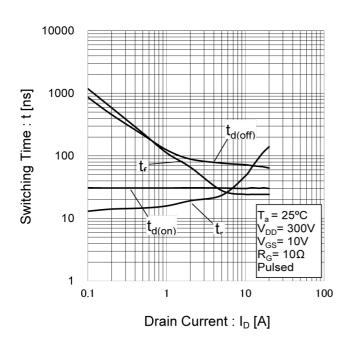
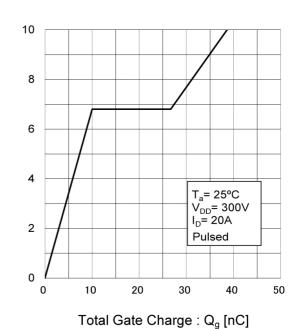


Fig.16 Typical Gate Charge



Gate - Source Voltage : V_{GS} [V]

Fig.17 Source Current vs. Source - Drain Voltage

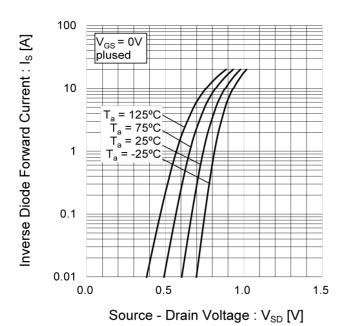
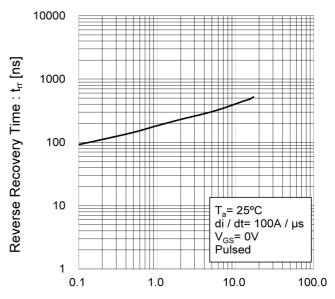


Fig.18 Reverse Recovery Time vs.
Inverse Diode Forward Current



Inverse Diode Forward Current : I_S [A]

Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

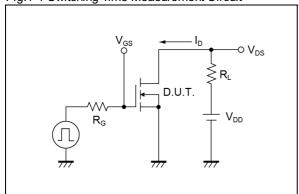


Fig.2-1 Gate Charge Measurement Circuit

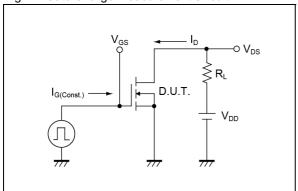


Fig.3-1 Avalanche Measurement Circuit

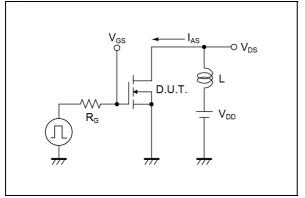


Fig.4-1 trr Measurement Circuit

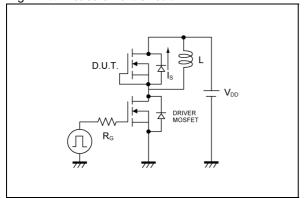


Fig.1-2 Switching Waveforms

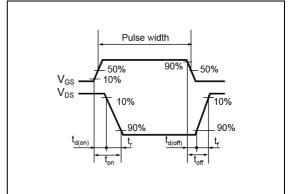


Fig.2-2 Gate Charge Waveform

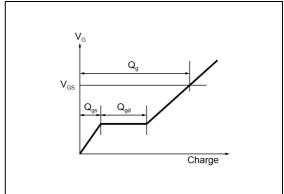


Fig.3-2 Avalanche Waveform

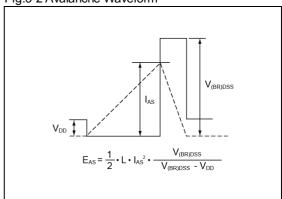
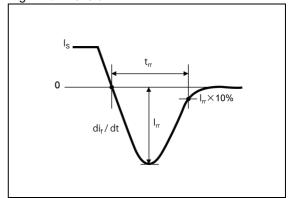
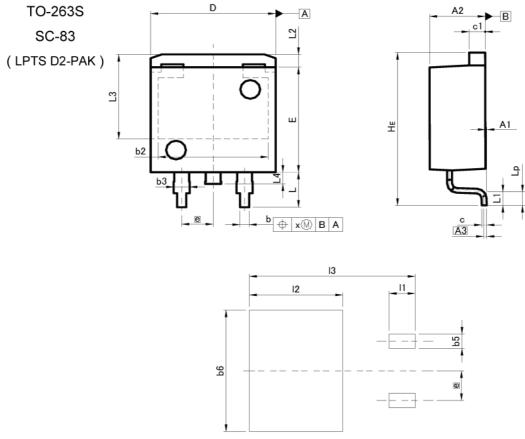


Fig.4-2 trr Waveform



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

| DIM | MILIM | ETERS | INC | HES |
|-----|-----------|-------|-------|-------|
| DIM | MIN | MAX | MIN | MAX |
| A1 | 0.00 | 0.30 | 0.000 | 0.012 |
| A2 | 4.30 | 4.70 | 0.169 | 0.185 |
| A3 | 0. | 25 | 0.0 | 10 |
| b | 0.68 | 0.98 | 0.027 | 0.039 |
| b2 | 8. | 90 | 0.3 | 50 |
| b3 | 1.14 | 1.44 | 0.045 | 0.057 |
| С | 0.30 | 0.60 | 0.012 | 0.024 |
| c1 | 1.10 | 1.50 | 0.043 | 0.059 |
| U | 9.80 | 10.40 | 0.386 | 0.409 |
| E | 8.80 | 9.20 | 0.346 | 0.362 |
| е | 2. | 54 | 0.1 | 00 |
| HE | 12.80 | 13.40 | 0.504 | 0.528 |
| L | 2.70 | 3.30 | 0.106 | 0.130 |
| L1 | 1. | 20 | 0.0 | 47 |
| L2 | 1. | 10 | 0.0 | 43 |
| L3 | 7.25 | | 0.2 | 85 |
| L4 | 1.00 | | 0.0 | 39 |
| Lp | 0.90 | 1.50 | 0.035 | 0.059 |
| Х | - | 0.25 | - | 0.010 |
| | | 7.777 | | |
| 1 | NATI TRAI | ETEDO | TNIO | IEC |

| DIM | MILIMETERS | | INC | HES |
|------|------------|-------|-----|-------|
| DIM | MIN | MAX | MIN | MAX |
| b5 | - | 1.23 | - | 0.049 |
| b6 | ī | 10.40 | 1 | 0.409 |
| . 11 | 1 | 2.10 | 1 | 0.083 |
| 12 | - | 7.55 | - | 0.297 |
| 13 | -0 | 13.40 | - | 0.528 |

Dimension in mm/inches



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|---------|-----------|------------|-----------|
| CLASSⅢ | CI ACCIII | CLASS II b | CI VCCIII |
| CLASSIV | CLASSII | CLASSⅢ | CLASSⅢ |

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- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
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- 8. Confirm that operation temperature is within the specified range described in the product specification.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
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- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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R6520KNJ - Web Page

| Part Number | R6520KNJ |
|-----------------------------|--------------|
| Package | LPTS (D2PAK) |
| Unit Quantity | 1000 |
| Minimum Package Quantity | 1000 |
| Packing Type | Taping |
| Constitution Materials List | inquiry |
| RoHS | Yes |